

ABSTRACT

A dicing die attach film, including an adhesive layer and a temporary-adhesive layer, the adhesive layer and the temporary-adhesive layer being
5 laminated,
wherein
the adhesive layer is a film-like adhesive layer containing an epoxy resin (A), an epoxy resin curing agent (B), a phenoxy resin (C), and an inorganic filler (D);
an elastic modulus of the phenoxy resin (C) at 25°C is 500 MPa or more;
10 in the adhesive layer, a proportion of the phenoxy resin (C) in total content of the epoxy resin (A) and the phenoxy resin (C) is 10 to 60% by mass;
a peeling strength between the adhesive layer and the temporary-adhesive layer at a range of 25 to 80°C is 0.40 N/25mm or less; and
a thermal conductivity of the adhesive layer after thermal curing is 1.0 W/m·K or
15 more.
(Fig.1)